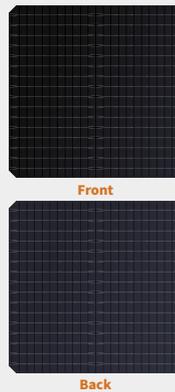


KEY FEATURES

 Low Optical Attenuation

 Lower Packaging Losses

 Anti-PID Performance



Size : 183.75mm*182.2mm±0.25mm

Thickness :130±13µm

Solderability: ≥0.9N

The results may vary depending to DS,welding methods and conditions.

Technical Data And Design

Light Intensity

	Intensity(W/m ²)	Uoc	Isc
Front (-): 16*0.05mmbusbar(silver),160fingers	1000	1.000	1.000
Back (+): 16*0.05mmbusbar(silver),184fingers	800	0.99	0.8
VOC factor: -0.3% / K	600	0.98	0.6
Current coefficient: + 0.048% / K	400	0.96	0.4
Power coefficient: -0.35% / K	200	0.93	0.2
Parallel resistance /reverse leakage: Rsh≥50Ω, Irev2≤1A			

Front Electrical Performance Parameters (Standard Test Conditions: 1000 W/m², AM1.5, 25°C)

No.	Eta (%)	Pmpp(W)	Uoc(V)	Isc(A)	FF (%)
1	25.5	8.54	0.7250	14.134	83.46
2	25.4	8.50	0.7241	14.134	83.24
3	25.3	8.47	0.7235	14.133	82.98
4	25.2	8.43	0.7220	14.130	82.83
5	25.1	8.40	0.7217	14.125	82.56
6	25.0	8.37	0.7207	14.120	82.40
7	24.9	8.33	0.7187	14.110	82.35
8	24.8	8.30	0.7166	14.107	82.27
9	24.7	8.27	0.7154	14.094	82.16
10	24.6	8.23	0.7141	14.081	82.06
11	24.5	8.20	0.7130	14.061	81.96
12	24.4	8.17	0.7122	14.048	81.80
13	24.3	8.13	0.7112	14.029	81.69
14	24.2	8.10	0.7100	14.015	81.57
15	24.1	8.07	0.7090	14.002	81.43
16	24.0	8.03	0.7082	13.983	81.28
17	23.9	8.00	0.7077	13.965	81.12

Iv Curve

